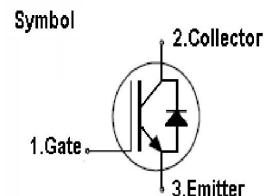
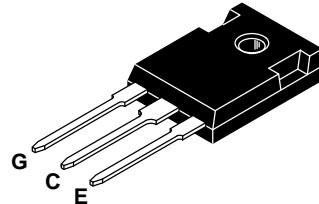


IGBT

PIN Connection TO-3P/TO-247

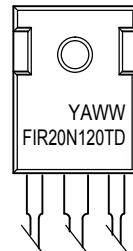
Features

- 1200V,20A,V_{ce(on)}(typ)=2.3V@V_{ge}=15V
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA using NPT technology



General Description

First semi NPT IGBTs offer lower losses and higher energy efficiency for application such as IH (induction heating), UPS, General inverter and other soft switching applications.

Marking Diagram


Y = Year
 A = Assembly Location
 WW = Work Week
 FIR20N120TD = Specific Device Code

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V _{CES}	Collector-Emitter Voltage	1200	V
V _{GES}	Gate-Emitter Voltage	± 30	V
I _c	Continuous Collector Current (T _C =25 °C)	40	A
	Continuous Collector Current (T _C =100°C)	20	A
I _{CM}	Pulsed Collector Current (Note 1)	80	A
I _F	Diode Continuous Forward Current (T _C =100 °C)	15	A
I _{FM}	Diode Maximum Forward Current (Note 1)	80	A
t _{sc}	Short Circuit Withstand Time	10	us
P _D	Maximum Power Dissipation (T _C =25 °C)	192	W
	Maximum Power Dissipation (T _C =100°C)	76	W
T _J	Operating Junction Temperature Range	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Max.	Units
R _{th j-c}	Thermal Resistance, Junction to case for IGBT	0.45	°C / W
R _{th j-c}	Thermal Resistance, Junction to case for Diode	0.85	°C / W
R _{th j-a}	Thermal Resistance, Junction to Ambient	40	°C / W

Electrical Characteristics (T_C=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	1200	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 1200V, V _{GE} = 0V	-	-	25	uA
I _{GES}	Gate Leakage Current, Forward	V _{GE} =30V, V _{CE} = 0V	-	-	100	nA
	Gate Leakage Current, Reverse	V _{GE} = -30V, V _{CE} = 0V	-	-	-100	nA
V _{GE(th)}	Gate Threshold Voltage	V _{GE} = V _{CE} , I _C = 250uA	4.5	5.0	5.5	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C = 20A	-	2.3	2.7	V
Q _g	Total Gate Charge	V _{CC} =600V V _{GE} =15V I _C =20A	-	100	120	nC
Q _{ge}	Gate-Emitter Charge		-	22	25	nC
Q _{gc}	Gate-Collector Charge		-	45	50	nC
t _{d(on)}	Turn-on Delay Time	V _{CC} =600V V _{GE} =15V I _C =20A R _G =28Ω Inductive Load T _C =25 °C	-	45	-	ns
t _r	Turn-on Rise Time		-	55	-	ns
t _{d(off)}	Turn-off Delay Time		-	350	-	ns
t _f	Turn-off Fall Time		-	80	-	ns
E _{on}	Turn-on Switching Loss		-	2.7	-	mJ
E _{off}	Turn-off Switching Loss		-	0.95	-	mJ
E _{ts}	Total Switching Loss		-	3.65	-	mJ
C _{ies}	Input Capacitance	V _{CE} =25V V _{GE} =0V f = 100kHz	-	619	-	pF
C _{oes}	Output Capacitance		-	109	-	pF
C _{res}	Reverse Transfer Capacitance		-	46	-	pF
R _{Gint}	Integrated gate resistor		2.0	2.5	3.0	Ω

Electrical Characteristics of Diode (T_C=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _F	Diode Forward Voltage	I _F =15A	-	1.35	1.5	V
t _{rr}	Diode Reverse Recovery Time	V _{CE} = 600V I _F = 15A dI _F /dt = 500A/us	-	210	245	ns
I _{rr}	Diode peak Reverse Recovery Current		-	27	30	A
Q _{rr}	Diode Reverse Recovery Charge		-	3300	3700	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature

Typical Performance Characteristics

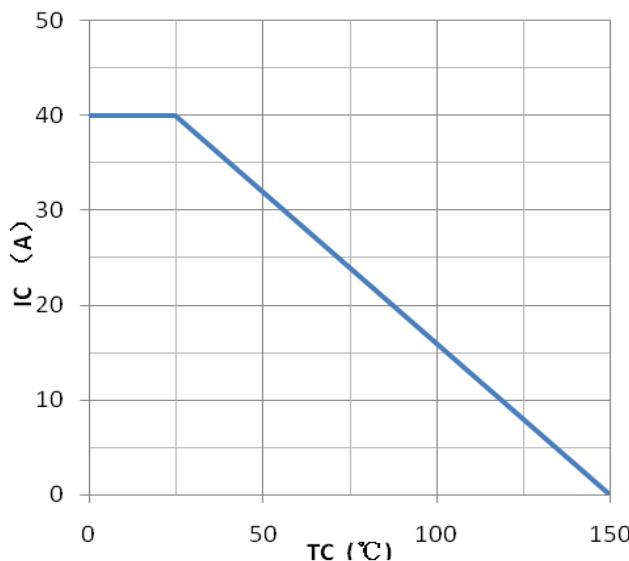


Figure1:maximum DC collector current VS. case temprature

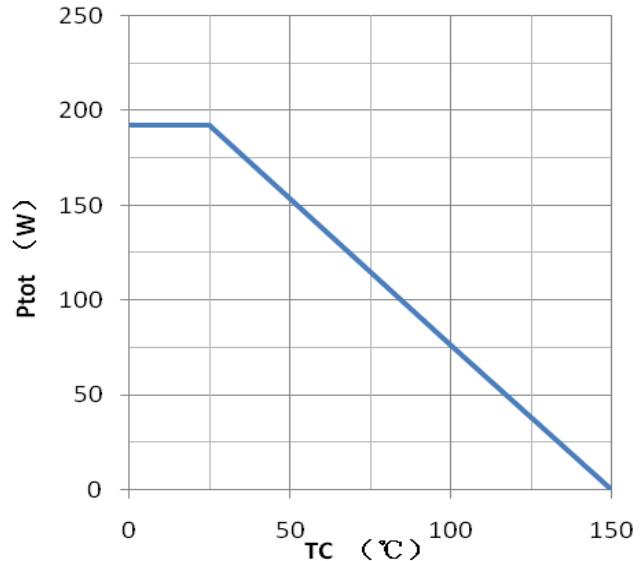


Figure2:power dissipation VS. case temprature

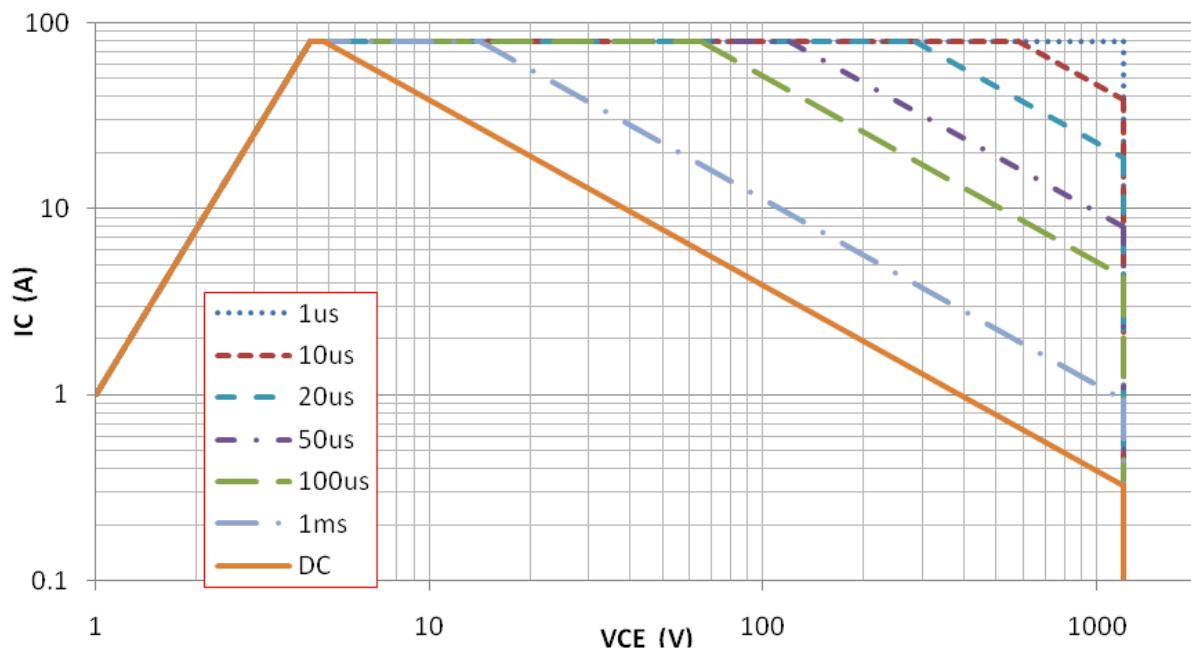


Figure3:forward SOA,TC=25°C,TJ≤150°C

Typical Performance Characteristics

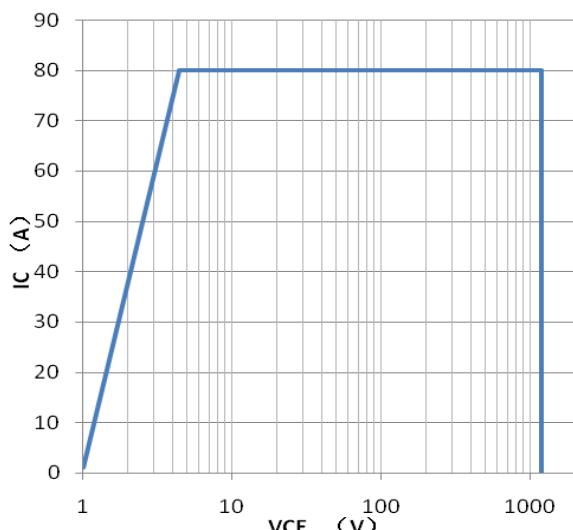


Figure 4: reverse bias SOA, $T_J=150^\circ\text{C}$, $V_{GE}=15\text{V}$

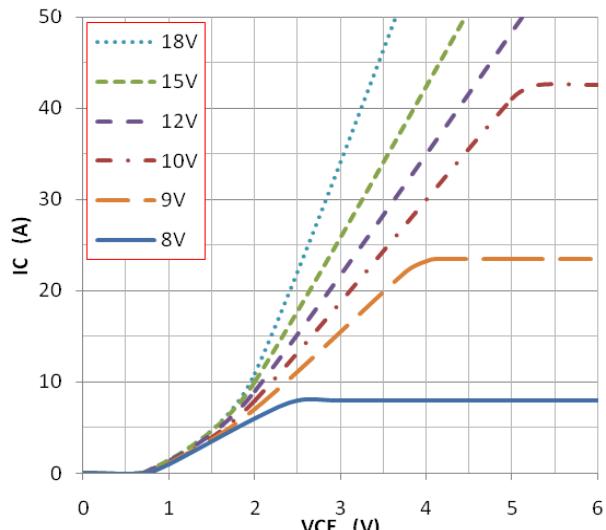


Figure 5: typical IGBT output characteristics,
 $T_J=25^\circ\text{C}$; $t_p=300\mu\text{s}$

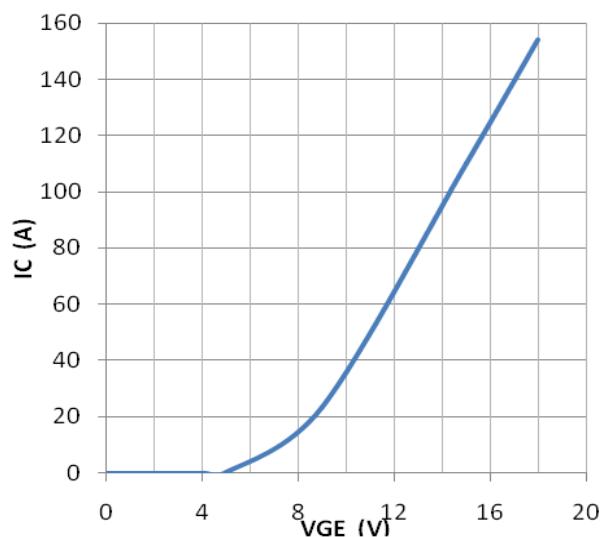


Figure 6: typical trans characteristics, $V_{CE}=20\text{V}$, $t_p=20\mu\text{s}$

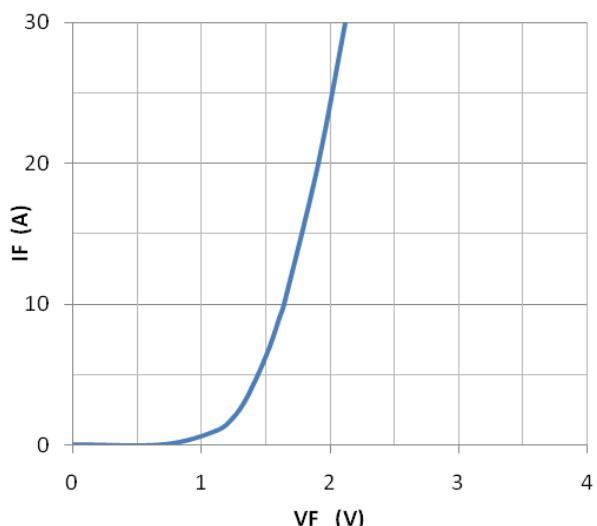


Figure 7: typical diode forward characteristic, $t_p=300\mu\text{s}$

Typical Performance Characteristics

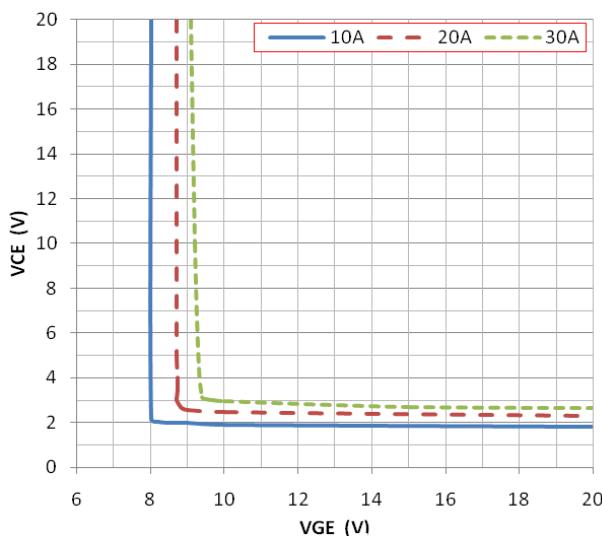


Figure 8: typical VCE VS. VGE, TJ=25°C

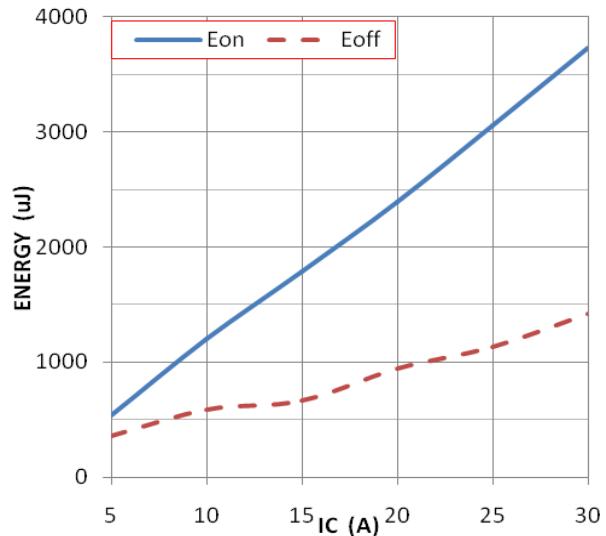


Figure 9: typical energy loss VS. IC, TC=25°C, L=500uH,
VCE=600V, VGE=15V, Rg=28Ω

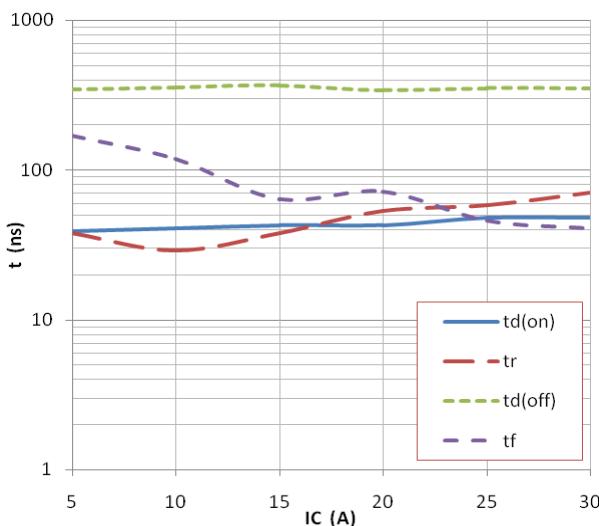


Figure 10: typical switching time VS. IC, TC=25°C,
L=500uH, VCE=600V, VGE=15V, Rg=28Ω

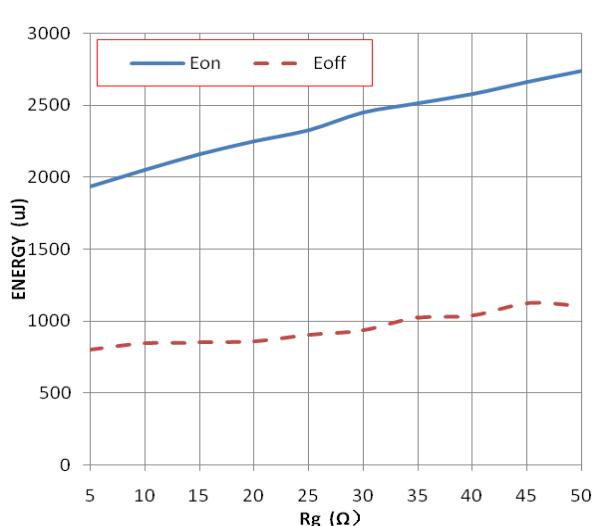


Figure 11: typical energy loss VS. Rg, TC=25°C,
L=500uH, VCE=600V, VGE=15V, IC=20A

Typical Performance Characteristics

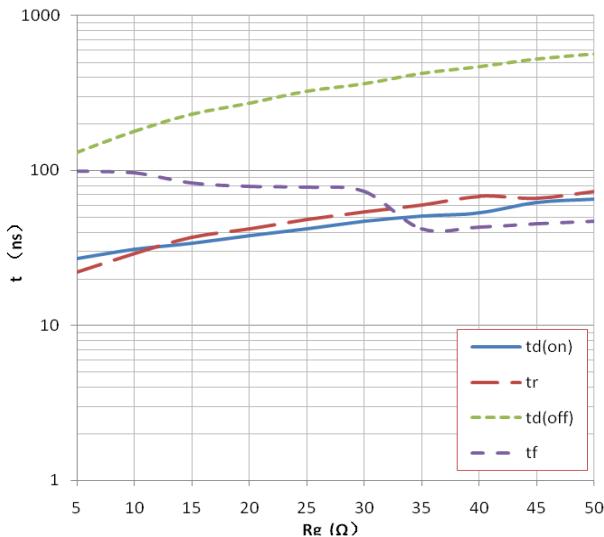


Figure11:typical switching time VS. Rg,TC=25°C ,
L=500uH,VCE=600V,VGE=15V,IC=20A

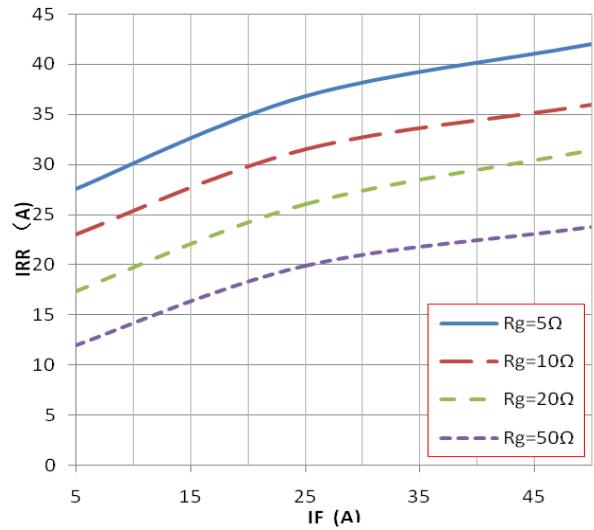


Figure12:typical diode IRR VS. IF, TC=25°C
VCC=600V,VGE=15V

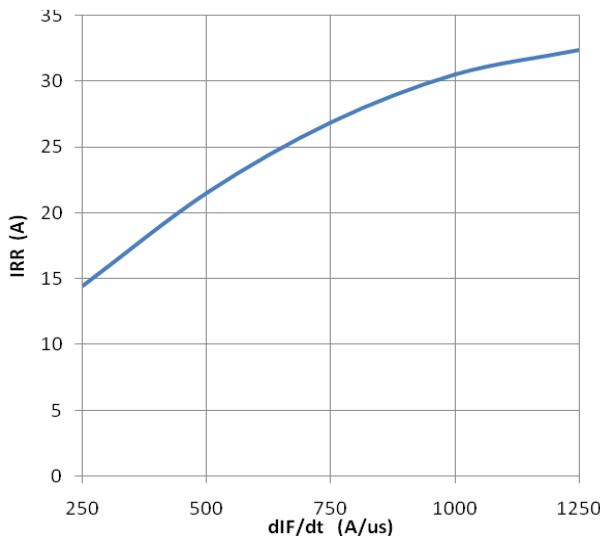


Figure13:typical diode IRR VS. dIF/dt
VCC=600V,VGE=15V,IF=20A

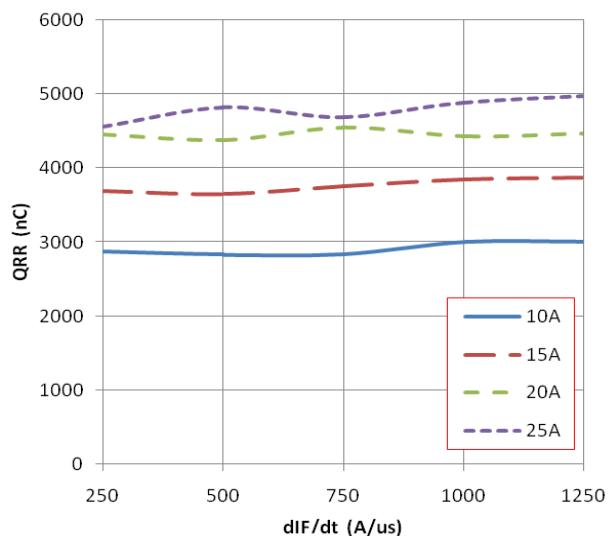


Figure14:typical diode QRR VS. dIF/dt
VCC=600V,VGE=15V

Typical Performance Characteristics

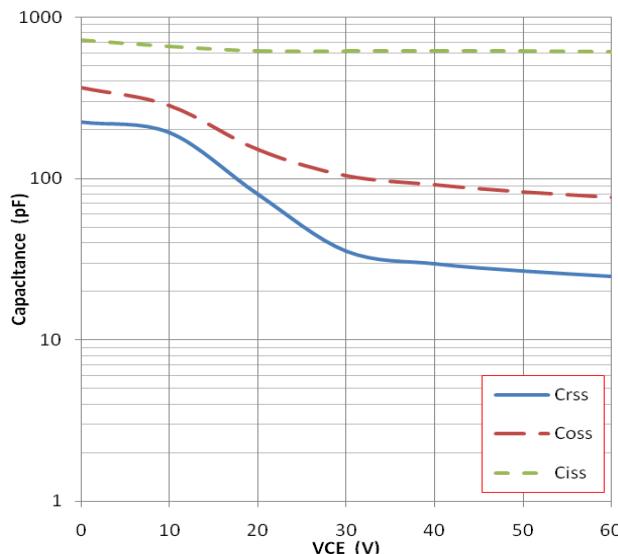


Figure15:typical capacitance VS. VCE,VGE=0V,f=100kHz

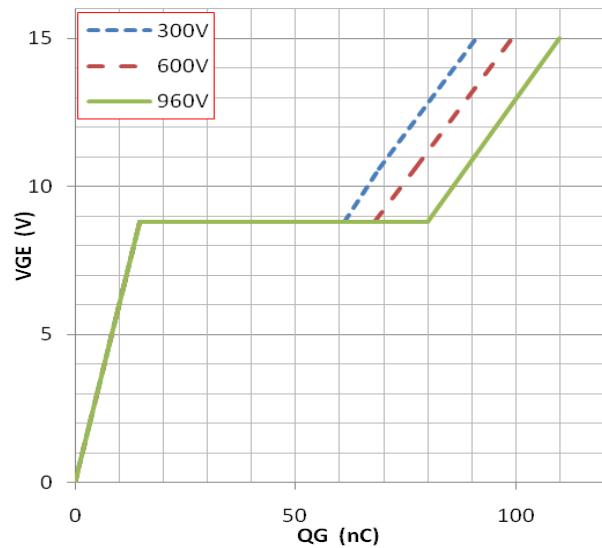


Figure16:typical gate charge VS. VGE,IC=20A

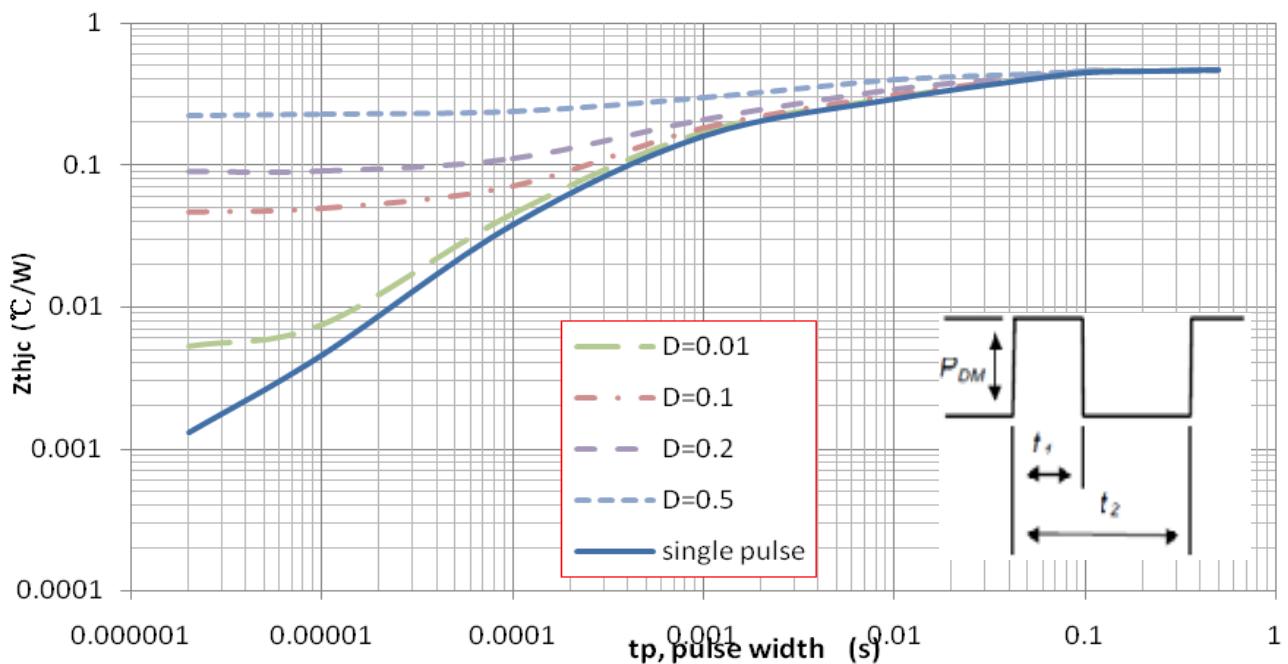


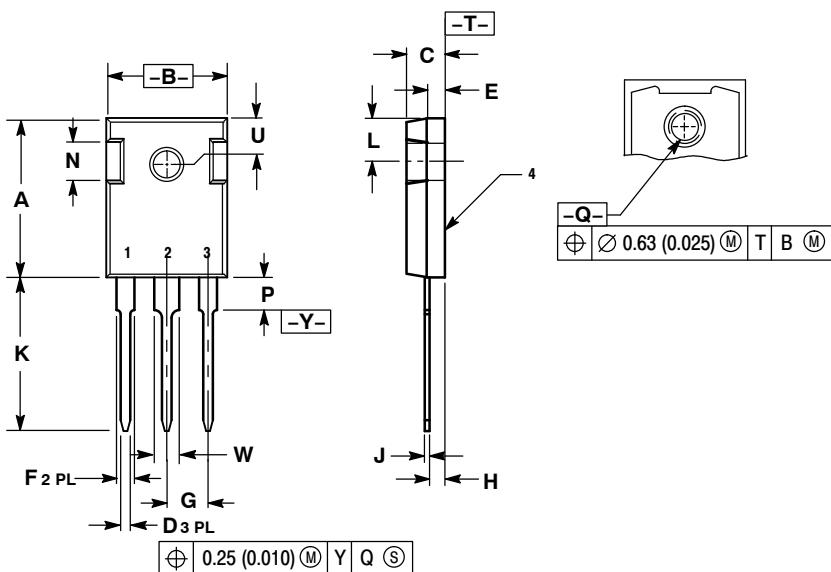
Figure19:normalized transient trermal impedance,junction-to-case

Note1.Duty factor $D=t_1/t_2$;

Note2:peak $T_J=PDM \times Zthjc + TC$

Package Dimensions

TO-3P/TO-247



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	20.32	21.08	0.800	0.830
B	15.75	16.26	0.620	0.640
C	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
E	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
H	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
M	4.32	5.49	0.170	0.216
P	----	4.50	----	0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123

STYLE 2:

1. ANODE
2. CATHODE (S)
3. ANODE 2
4. CATHODES (S)